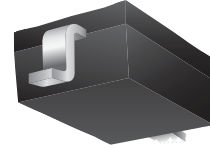




Product Change Notification

CHIP DIODES

Bourns Manufacturers Representatives
Corporate Distributor Product Managers
Americas Sales Team
Asia Sales Team
Europe Sales Team



February, 2010

Bourns® Diode Products Addition of Second Wafer Fabrication Location and Change to “Green” Compliance

Bourns is adding a second wafer fabrication location, in the UK, for the diode part numbers below for continued secure supply chain management and delivery support to our customers.

Bourns P/N	Bourns P/N
CDSOD323-T05	CDSOD323-T05L
CDSOD323-T05C	CDSOD323-T05LC
CDSOD323-T08	CDSOD323-T08L
CDSOD323-T08C	CDSOD323-T08LC
CDSOD323-T12	CDSOD323-T12L
CDSOD323-T12C	CDSOD323-T12LC
CDSOD323-T15	CDSOD323-T15L
CDSOD323-T15C	CDSOD323-T15LC
CDSOD323-T18	CDSOD323-T18L
CDSOD323-T18C	CDSOD323-T18LC
CDSOD323-T24	CDSOD323-T24L
CDSOD323-T24C	CDSOD323-T24LC

Bourns will change to the Green Sumitomo G600 mold compound in the above packages pursuant to our plan to offer “Green” products to our customers in 2010.

Some products will be available in the new “Green” mold compound immediately if requested by customers.

Reliability data, SGS and MDS reports on the units’ package assembly incorporating the above changes will be available on or before March 31, 2010.

Bourns is issuing 90 days notice that mass production using the above changes will be available beginning May 17, 2010.